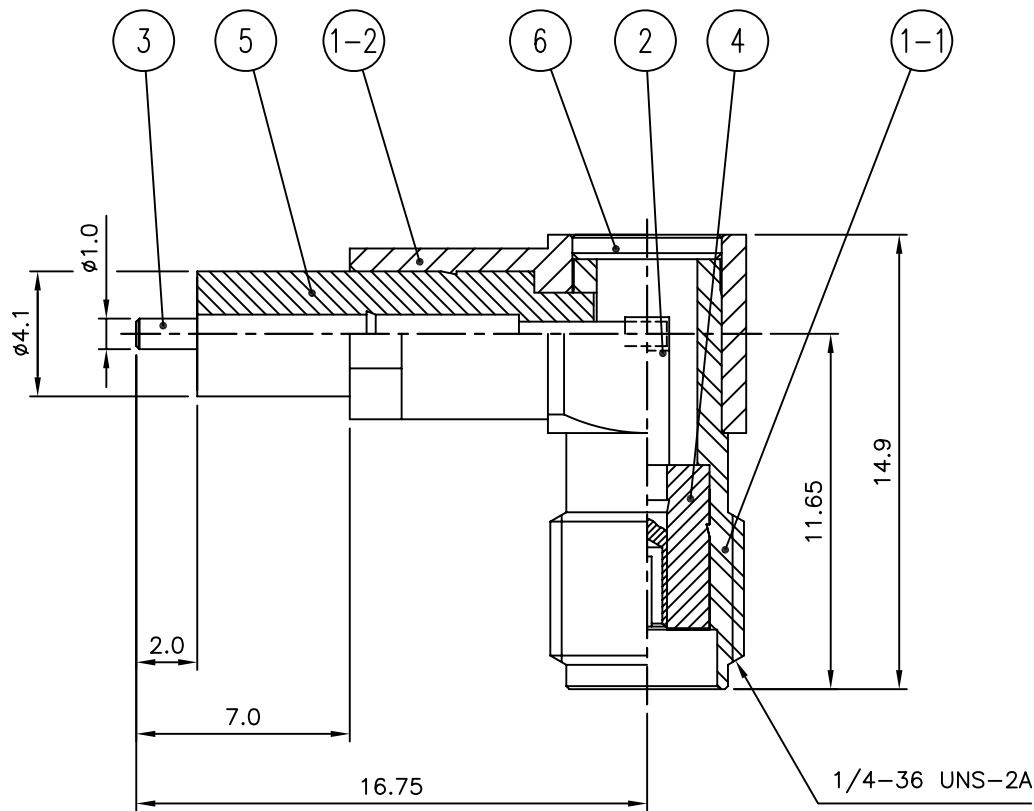
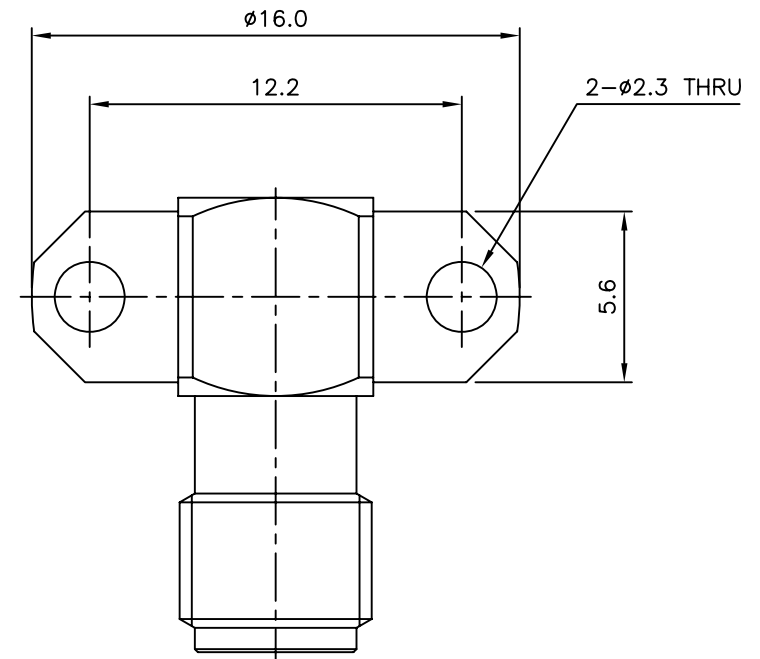




REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	C.K.KIM	I.C.KIM	2016.08.30.



조립순서

- ④번 TEFLON에 ②번 PIN을 조립한다.
- ⑤번 TEFLON에 ③번 PIN을 조립한다.
- ④+②번을 1-1(A) BODY에 조립한다.
- ⑤+③번을 1-2(B) BODY에 조립한다.
- ②번, ③번 PIN을 SOLDER 한다.
- ⑥번 COVER를 조립한다.

* 커플링 토크 관리규격 0.9~1.1N·m

6	COVER	1	MBsBD C3604BD-F	Nickel Plate	DCO00023-5/2
5	INSULATOR	1	TEFLON		DIN02830-N/1
4	INSULATOR	1	TEFLON		DIN01973-N/1
3	CONTACT	1	MBsBD C3604BD-F	Gold Plate	DCT03757-5/1
2	CONTACT	1	BeCu C17300	Gold Plate	DCT03756-5/1
1	1-2 BODY(B)	1	MBsBD C3604BD-F	Nickel Plate	DBB00450-5/1
	1-1 BODY(A)	1	MBsBD C3604BD-F	Nickel Plate	DBD04225-1/1 DBD04226-3/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2016. 08. 30.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	I.C.KIM	
MATERIAL		CHECKED BY		TITLE SMA50 SOLDER END JL-2H
		DRAWN BY	C.K.KIM	
FINISH		SCALE	4/1	DWG NO. CN03643-7/1
		UNIT	mm	
		A4		REVISION I R
				SHEET 1 of 1